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In the abstract:

Please amend the abstract as follows:

~~Arrangement with light-emitting power semiconductor device and method for fabricating same~~

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A light-emitting power semiconductor device (3) is placed on a metallic substrate structure (4) with the formation of a good heat-transfer contact. ~~A~~, in which a plastic protective body (9) surrounds the power semiconductor device (3), leaving exposed a light exit region (8) in the nature of a cap.

(Fig. 1)
